



TITLE: INTEGRATED CIRCUIT PACKAGE HAVING BYPASS CAPACITORS  
COUPLED TO BOTTOM OF PACKAGE SUBSTRATE AND SUPPORTING  
SURFACE MOUNTING TECHNOLOGY

INVENTOR(S): Behdad Jafari and Ray Chen

USSN: 10/717,342 ATTORNEY DOCKET #: NVID-P000730

1/8

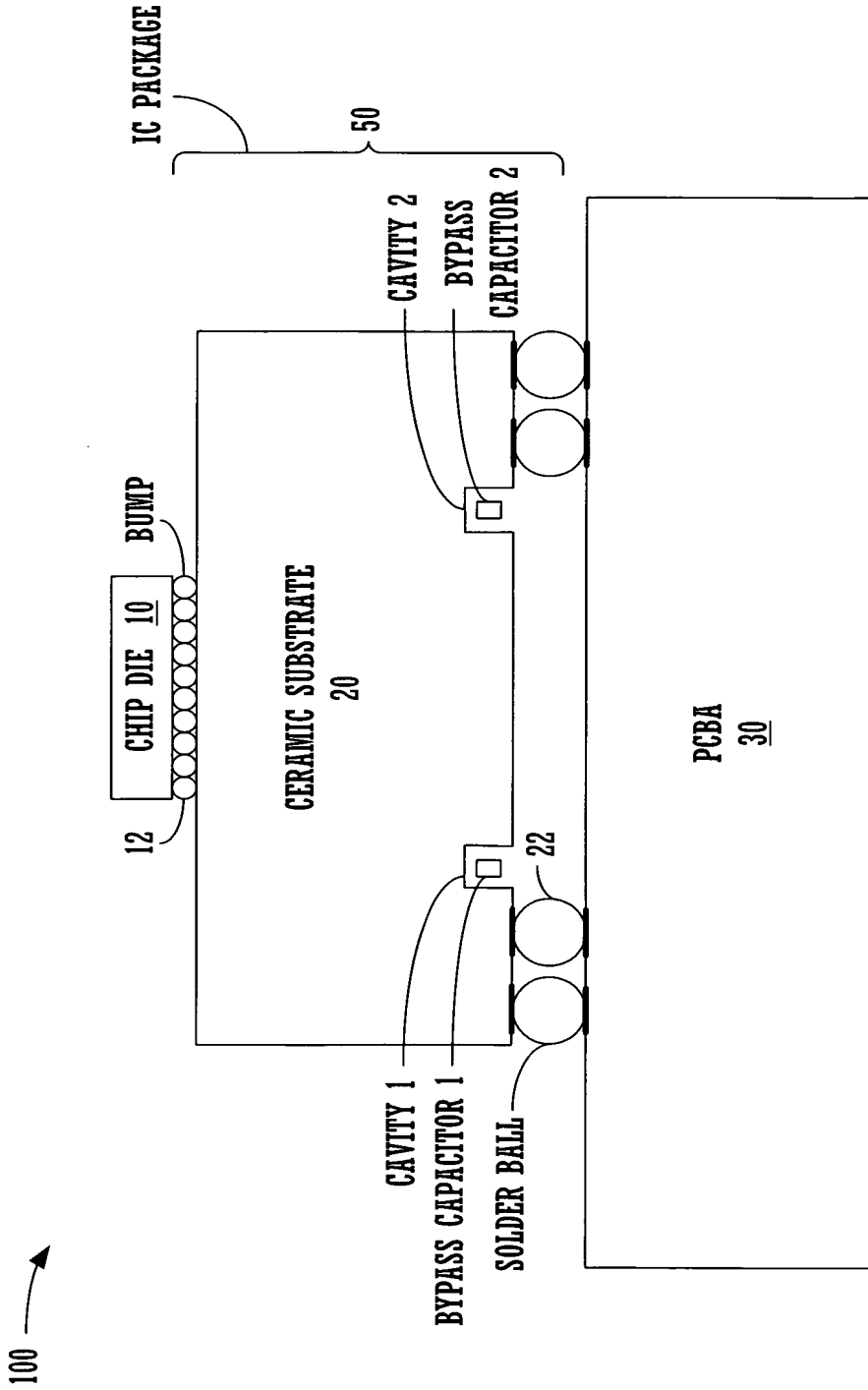


FIGURE 1  
(Prior Art)

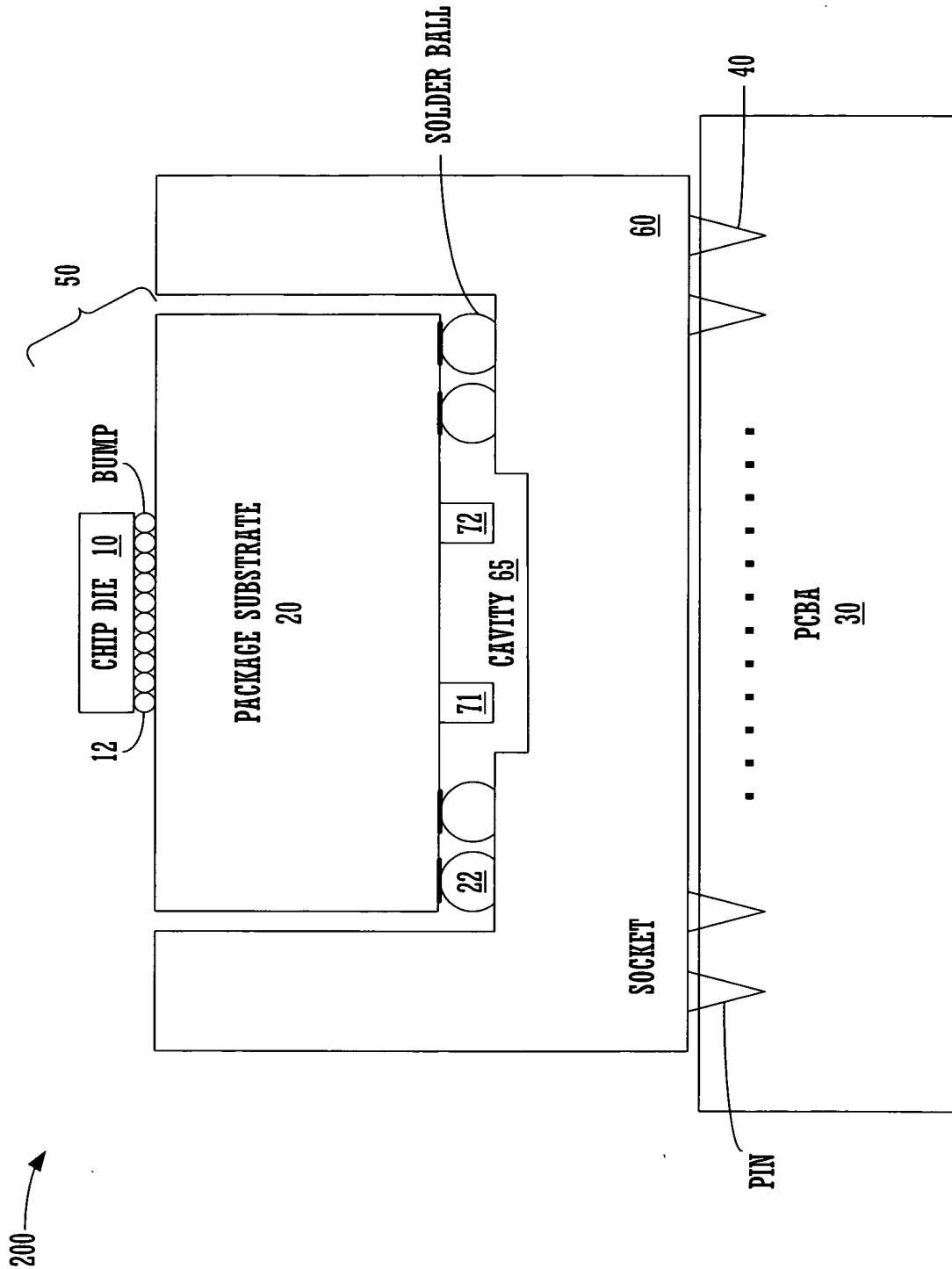


FIGURE 2  
 (Prior Art)

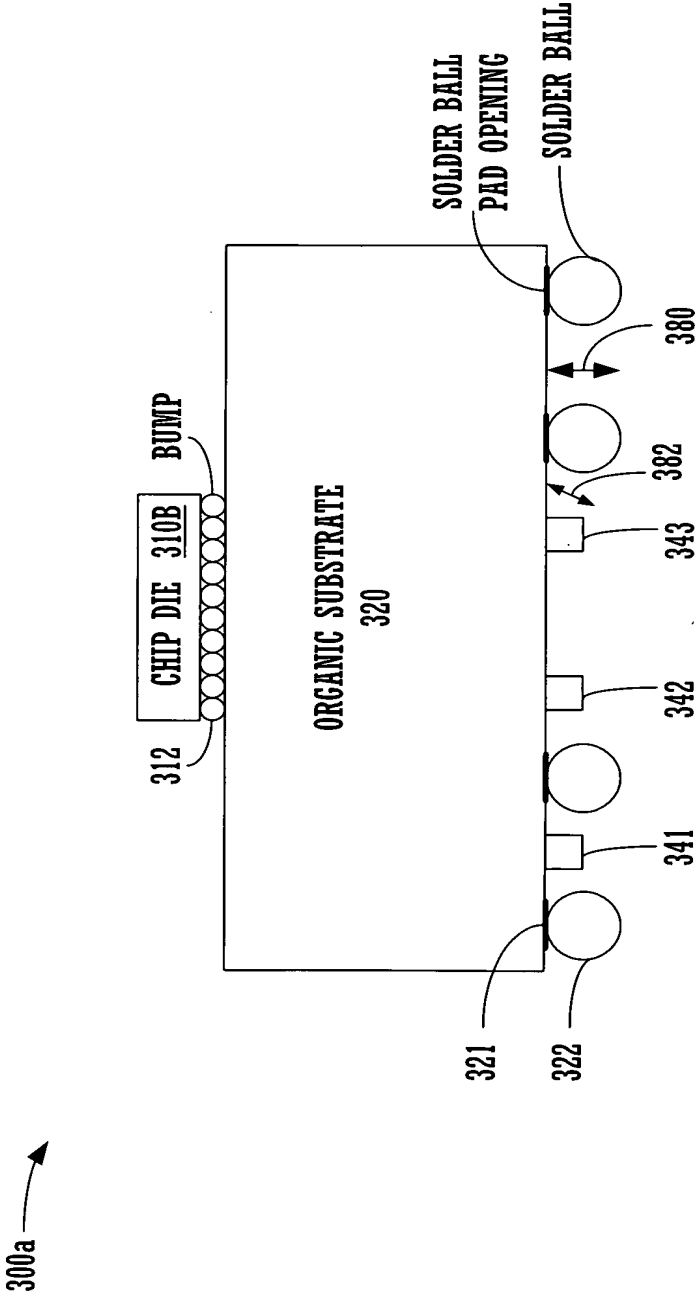


FIGURE 3A

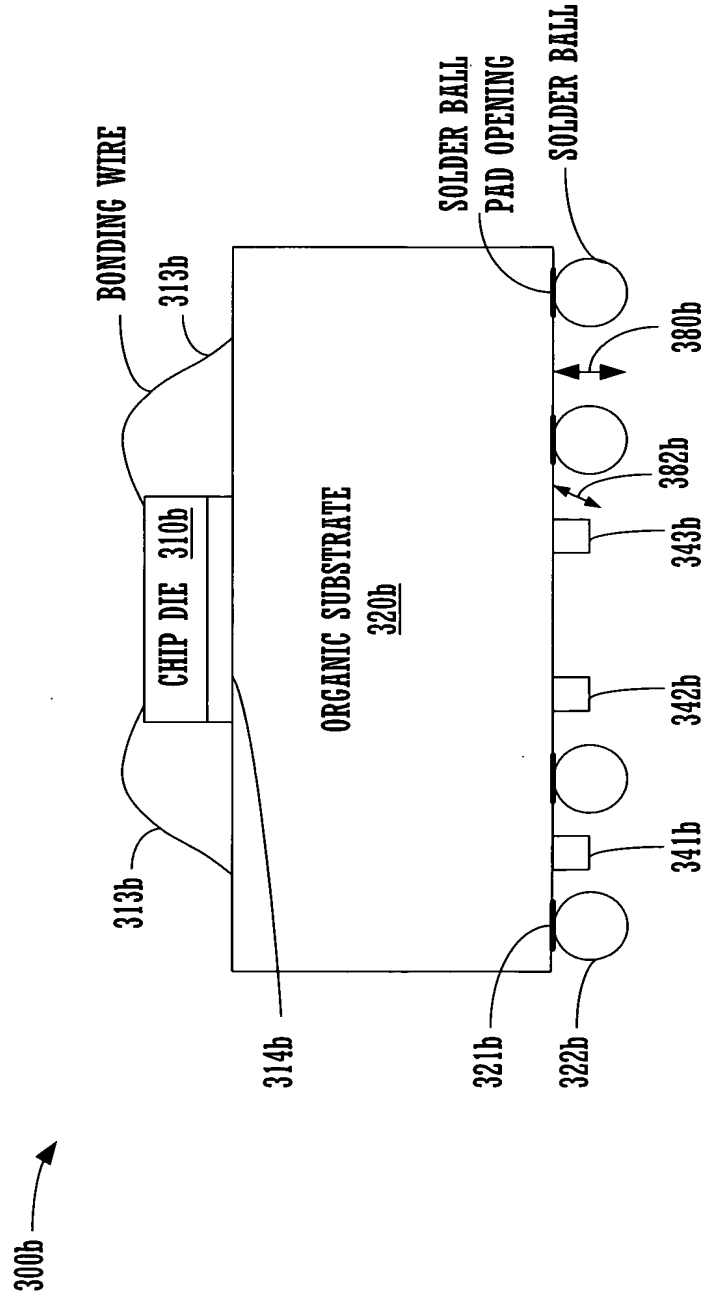


FIGURE 3B

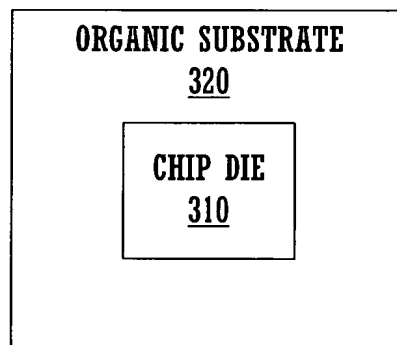
TITLE: INTEGRATED CIRCUIT PACKAGE HAVING BYPASS CAPACITORS  
COUPLED TO BOTTOM OF PACKAGE SUBSTRATE AND SUPPORTING  
SURFACE MOUNTING TECHNOLOGY

INVENTOR(S): Behdad Jafari and Ray Chen

USSN: 10/717,342 ATTORNEY DOCKET #: NVID-P000730

5/8

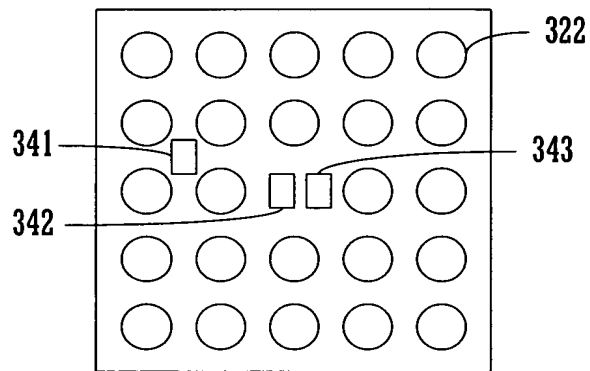
**TOP VIEW**



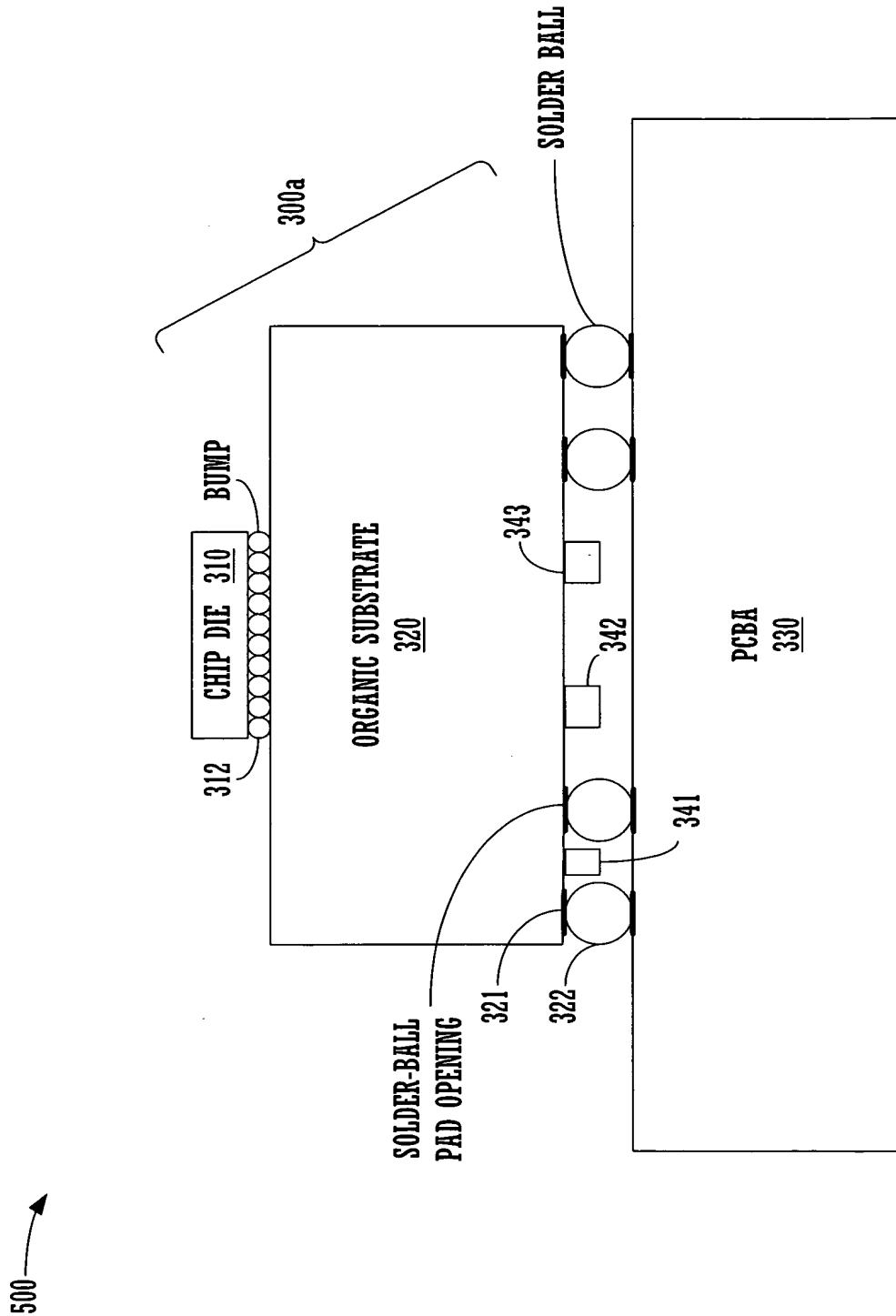
**FIGURE 4A**

6/8

**BOTTOM VIEW**



**FIGURE 4B**



8/8

600

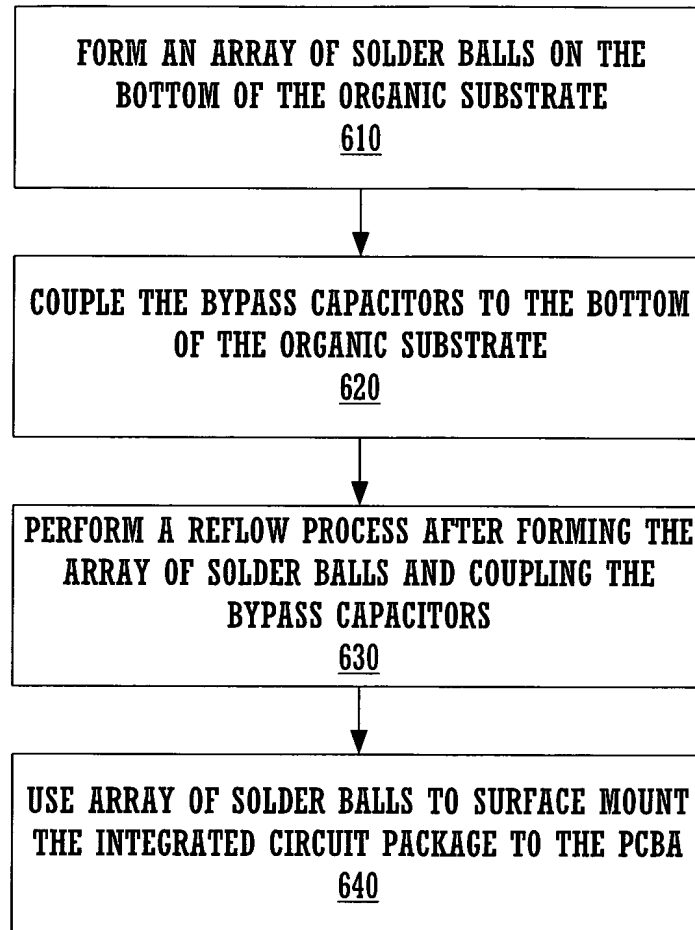


FIGURE 6